## Intel<sup>®</sup> Core<sup>™</sup> i3-6100TE Processor (4M Cache, 2.70 GHz)

Specifications			
- Essentials			
Status Launched			
Launch Date	Q4'15		
Processor Number	i3-6100TE		
Intel® Smart Cache	4 MB		
DMI3	8 GT/s		
Instruction Set	64-bit		
Instruction Set Extensions	SSE4.1/4.2, AVX 2.0		
Embedded Options Available	Yes		
Lithography	14 nm		
Scalability	1S Only		
Thermal Solution Specification	PCG 2015A (35W)		
Recommended Customer Price	TRAY: \$117.00		
Conflict Free Yes			
Datasheet Link			
- Performance			
# of Cores	2		
# of Threads	4		
Processor Base Frequency	2.7 GHz		
<u>TDP</u> 35 W			
- Memory Specifications			
Max Memory Size (dependent on memory type) 64 GB			
Memory Types DDR4-1866/2133, DDR3L-1333/1600 @ 1.35V			
lax # of Memory Channels 2			
lax Memory Bandwidth 34.1 GB/s			
ECC Memory Supported <sup>‡</sup>	Yes		
- Graphics Specifications			
Processor Graphics <sup>‡</sup> Intel <sup>®</sup> HD Graphics 530			
Graphics Base Frequency 350 MHz			
Graphics Max Dynamic Frequency	1 GHz		
Graphics Video Max Memory	64 GB		
Graphics Output	eDP/DP/HDMI/DVI		

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Max Resolution (MGA)*         4096/2304@60Hz           Max Resolution (MGA)*         NA           Directif: Support         12           QeenSif: Support         44           Directif: Support         44           Resolution (MGA)*         Ves           Intel: Outk Sync Video         §           Vest         Vest           Intel: Initiation         Vest           Intel: National Sync Video         Vest           Intel: Curk Video Technology         Vest           Package Specifications         Jointa State           Intel: Curk Video Technology         Intel: State           Intel: Curk Video Technology         Intel: State           Intel: Curk Video Tec	Max Resolution (HDMI 1.4)‡	4096x2304@24Hz	
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Quencial.'support         44           Nuck Sync Video         Yes           Intel* Ouick Sync Video         Yes           Intel* Intru" 3D.Technology         Yes           Intel* Intru" 3D.Technology         Yes           Intel* Mincless Display         Yes           Intel* Clear Video ID.Technology         Yes           Intel* Clear Video Technology         Jon           Intel* Clear Video Technology         Jon           Intel* Not Clear Video Technology         Jon           Intel* Video Technology         Jon           Intel* Clear Video Technology         Intel* Yes           Intel* Video Technology         So Technology           Intel* Video Technology         Intel* Yes           Intel* Video Technology         No           Intel* Yes         Yes	Max Resolution (VGA)‡	N/A	
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intel*inded**         Yes           Intel*Wireles Display         Yes           Intel*Clear Video HD Technology         Yes           Intel*Clear Video Technology         Yes           PECExpress Revision         30           PCExpress Configurations*         Up to 1x16, 2x8, 1x8+2x4           Max do PCI Express Lanes         16           Package Specifications         Yes           Review Configuration         1           Package Specifications         1           Verdage Options Available         14 nm           Sockets Supported         See MDDS           Intel* Verdenology1         No           Intel*	Intel® Quick Sync Video	Yes	
Intel® Wireles Display         Wes           Intel® Vices Dischnology         Yes           Intel® Clear Vice Dischnology         Yes           Device Di         Origitations           Package Specifications <sup>1</sup> Jo           Package Specifications         Io           Package Specifications         Intel® Clear Vice Discover           Socket Supported         Intel® Clear Vice Discover           Socket Supported         School Stand MC Libography           Intel® Vice Discover         School Stand MC Libography           Intel® Turbo Boost Technology 1         No           Intel® Vicualization Technology (VT-N) <sup>1</sup> Ves           Intel® Vicualization Technology (VT-N) <sup>1</sup> Yes           Intel® Vicualization T	Intel® InTru™ 3D Technology	Yes	
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interface         3           bevice iD         0x1912           c         xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx	Intel® Clear Video HD Technology	Yes	
Device ID         ox1912           • Expansion Options         30           PCI Express Revision         30           PCI Express Configurations 1         Up to 1x16,2x8,1x8+2x4           Max # of PCI Express Lanes         16           • Package Specifications         1           Max CPU Configuration         1           Package Specifications         37.5mm x 37.5mm           Graphics and IMC Lithography         44 nm           Sockets Supported         FCIGA1151           Low Halogen Options Available         See MDDS           • Advanced Technology. <sup>1</sup> No           Intel® Yurualization Technology. <sup>1</sup> Ves           Intel® Yurualization Technology for Directed I/O (VT.d). <sup>1</sup> Ves           Intel® Yurualization Technology for Directed I/O (VT.d). <sup>1</sup> Ves           Intel® Yurualization Technology for Directed I/O (VT.d). <sup>1</sup> Ves           Intel® Yurualization Technology for Directed I/O (VT.d). <sup>1</sup> Ves           Intel® States         No	Intel® Clear Video Technology	Yes	
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- Advanced Technologies Intel® Turbo Boost Technology ‡ No Intel® VPro Technology ‡ No Intel® Hyper-Threading Technology ‡ Ves Intel® Virtualization Technology (VT-x) ‡ Yes Intel® Virtualization Technology for Directed I/O (VT-d) ‡ Yes Intel® VT-x with Extended Page Tables (EPT) ‡ No Intel® TSX-NI No Intel® 64 ‡ Yes	Sockets Supported	FCLGA1151	
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Intel® vPro Technology ‡NoIntel® vPro Technology ‡VesIntel® Hyper-Threading Technology (VT-x) ‡YesIntel® Virtualization Technology (VT-x) ‡YesIntel® Virtualization Technology for Directed I/O (VT-d) ‡YesIntel® TSX-NINoIntel® 64 ‡YesIntel® 64 ‡YesIde StatesYes		No	
Intel® Hyper-Threading Technology ‡       Image: Second Seco			
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Intel® VT-x with Extended Page Tables (EPT) <sup>‡</sup> Yes        Intel® TSX-NI     No       Intel® 64 <sup>‡</sup> Yes       Idle States     Yes			
Intel® TSX-NI         No           Intel® 64 ‡         Yes           Idle States         Yes			
Intel® 64 ‡     Yes       Idle States     Yes			
Idle States     Yes			
	-		

Thermal Monitoring Technologies	Yes		
Intel® Identity Protection Technology <sup>‡</sup>	Yes		
Intel® Stable Image Platform Program (SIPP)	No		
Intel® Small Business Advantage	Yes		
- Intel® Data Protection Technology			
Intel® AES New Instructions	Yes		
Secure Key	Yes		
Intel® Software Guard Extensions (Intel® SGX)	Yes		
Intel® Memory Protection Extensions (Intel® MPX)	Yes		
- Intel® Platform Protection Technology			
OS Guard	Yes		
Trusted Execution Technology <sup>‡</sup>	No		
Execute Disable Bit <sup>‡</sup>	Yes		

# Compatible Products

## - Chipsets

Compare	Product Name	Status	Embedded Options Available	TDP	Recommended Customer Price
Compare All +					
	Intel® H170 Chipset (Intel® GL82H170 PCH)	Launched	No	6 W	T&R:\$32.00
	Intel® H110 Chipset (Intel® GL82H110 PCH)	Launched	Yes	6 W	T&R:\$26.00
	Intel® Z170 Chipset (Intel® GL82Z170 PCH)	Launched	No	6 W	T&R : \$47.00
	Intel® Q170 Chipset (Intel® GL82Q170 PCH)	Launched	Yes	6 W	T&R : \$47.00
	Intel® Q150 Chipset (Intel® GL82Q150 PCH)	Launched	No	6 W	T&R : \$43.00
	Intel® B150 Chipset (Intel® GL82B150 PCH)	Launched	No	6 W	T&R : \$28.00

## Ordering and Spec Information

#### Trade Compliance Information

	ECCN	CCATS	US HTS
5A99		G077159	8542310000

### Ordering and Spec Information

Spec Code	Ordering Code	Step	RCP
Intel® Core™ i3-6100TE Processor (4M Cache, 2.70 GHz) FC-LGA14C, Tray			

SR2LS	CM8066201938603	RO	\$117.00

### **Download Drivers**

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

<sup>‡</sup> This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel also uses the term "conflict-free" before January 1, 2013 are not confirmed conflict free. The conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel<sup>®</sup> Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see http://www.intel.com/performance.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See <a href="http://www.intel.com/content/www/us/en/processors/processor-numbers.html">http://www.intel.com/content/www/us/en/processor numbers.html</a> for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

Send us your feedback!